MC74HCT4094A

8-Bit Shift and Store Register with LSTTL Compatible Inputs

High−Performance Silicon−Gate CMOS

The MC74HCT4094A is a high speed CMOS 8−bit serial shift and storage register. This device consists of an 8−bit shift register and latch with 3−state output buffers. Data is shifted on positive clock (CP) transitions. The data in the shift register is transferred to the storage register when the Strobe (STR) input is high. The output buffers are enabled when the Output Enable (OE) input is set high. Two serial outputs (QS_1, QS_2) are available for cascading multiple devices.

The MC74HCT4094A can be used to interface TTL or CMOS outputs to high speed CMOS inputs.

Features

- Wide Operating Voltage Range: 4.5 to 5.5 V
- Low Power Dissipation: I_{CC} = < 10 μA
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- These are Pb−Free Devices

Typical Applications

- Serial−to−Parallel Conversion
- Remote Control Storage Register

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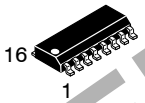
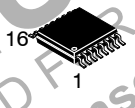
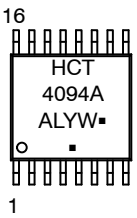
MARKING DIAGRAMS



SOIC−16
D SUFFIX
CASE 751B



TSSOP−16
DT SUFFIX
CASE 948F



A	=	Assembly Location
WL, L	=	Wafer Lot
YY, Y	=	Year
WW, W	=	Work Week
G, ▪	=	Pb−Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

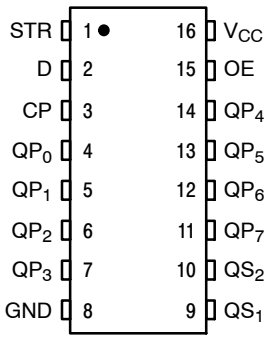


Figure 1. Pin Assignment

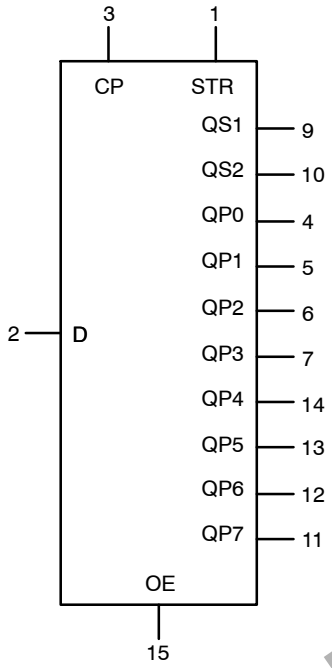


Figure 2. Logic Symbol

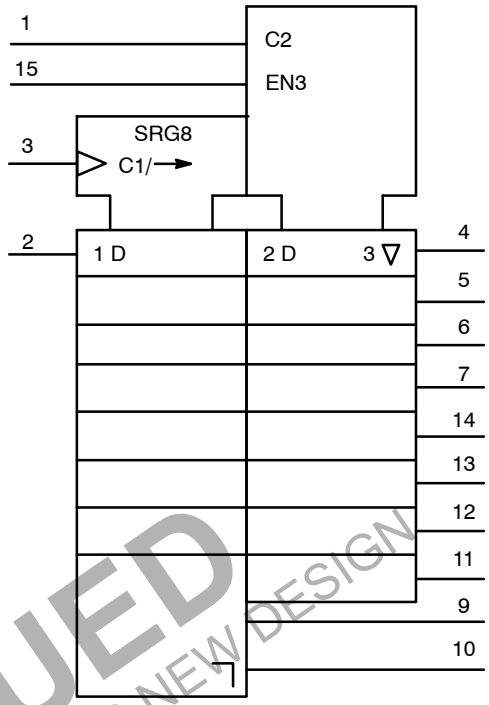


Figure 3. IEC Logic Symbol

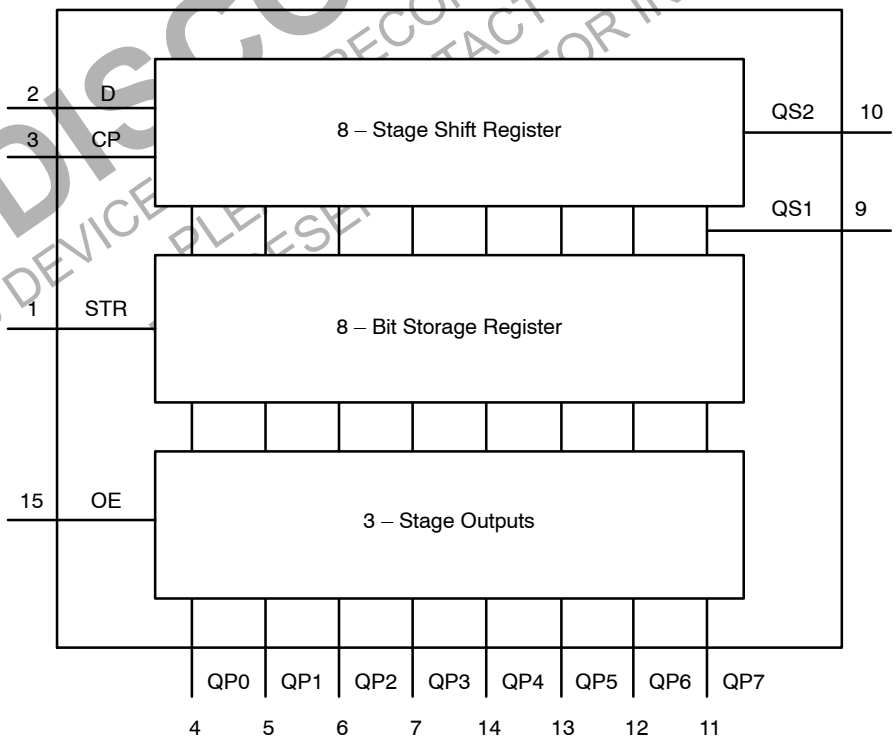


Figure 4. Functional Diagram

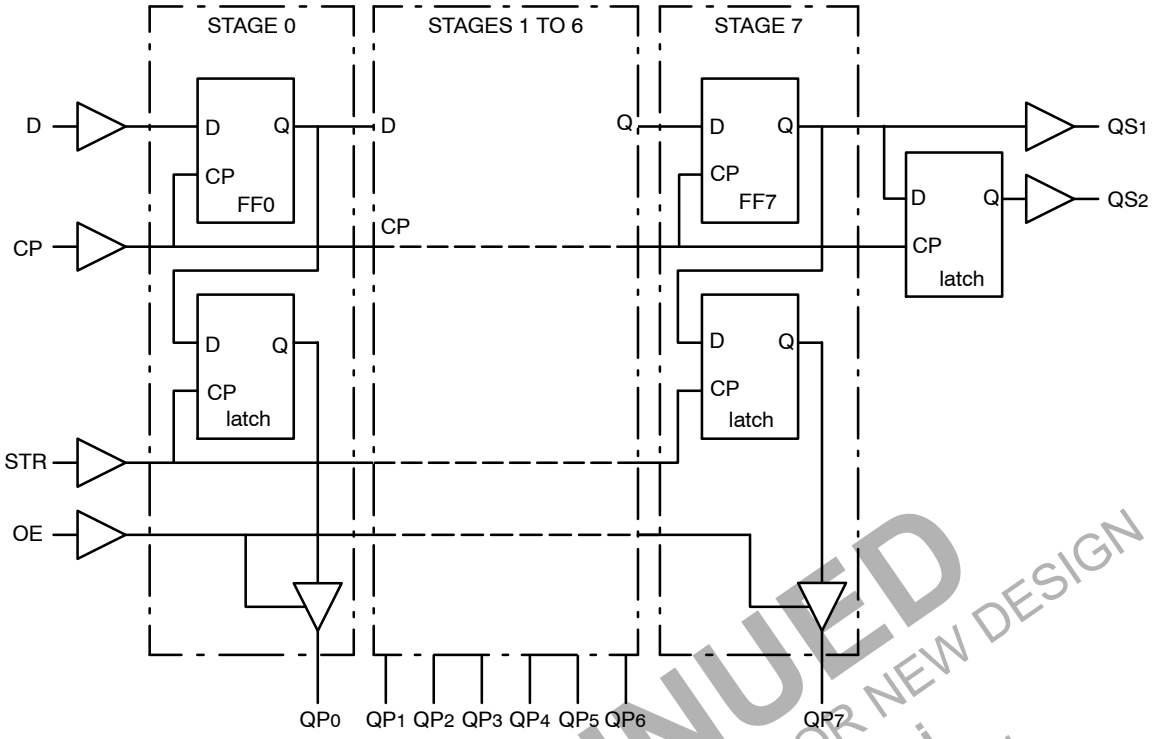


Figure 5. Logic Diagram

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	– 0.5 to + 7.0	V
V_{in}	DC Input Voltage (Referenced to GND)	– 0.5 to V_{CC} + 0.5	V
V_{out}	DC Output Voltage (Referenced to GND)	– 0.5 to V_{CC} + 0.5	V
I_{in}	DC Input Current, per Pin	± 20	mA
I_{out}	DC Output Current, per Pin	± 35	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins	± 75	mA
P_D	Power Dissipation in Still Air, SOIC Package†	500	mW
	TSSOP Package†	450	
T_{stg}	Storage Temperature	– 65 to + 150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

†Derating – SOIC Package: – 7 mW/°C from 65° to 125°C
TSSOP Package: – 6.1 mW/°C from 65° to 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND ≤ (V_{in} or V_{out}) ≤ V_{CC}.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	4.5	5.5	V
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Referenced to GND)	0	V_{CC}	V
T_A	Operating Temperature, All Package Types	–55	+125	°C
t_r, t_f	Input Rise and Fall Time (Figure 1)	0	500	ns

FUNCTIONAL TABLE

INPUTS				PARALLEL OUTPUTS		SERIAL OUTPUTS	
CP	OE	STR	D	QP0	QPn	QS1	QS2
↑	L	X	X	Z	Z	Q'6	NC
↓	L	X	X	Z	Z	NC	QP7
↑	H	L	X	NC	NC	Q'6	NC
↑	H	H	L	L	QPn−1	Q'6	NC
↑	H	H	H	H	QPn−1	Q'6	NC
↓	H	H	H	NC	NC	NC	QP7

Notes

1. H = HIGH voltage level
   L = LOW voltage level
   X = don't care
   Z = high impedance OFF−state
   NC = no change
   ↑ = LOW−to−HIGH CP transition
   ↓ = HIGH−to−LOW CP transition
   Q'6 = the information in the seventh register stage is transferred to the 8th register stage and QSn output at the positive clock edge

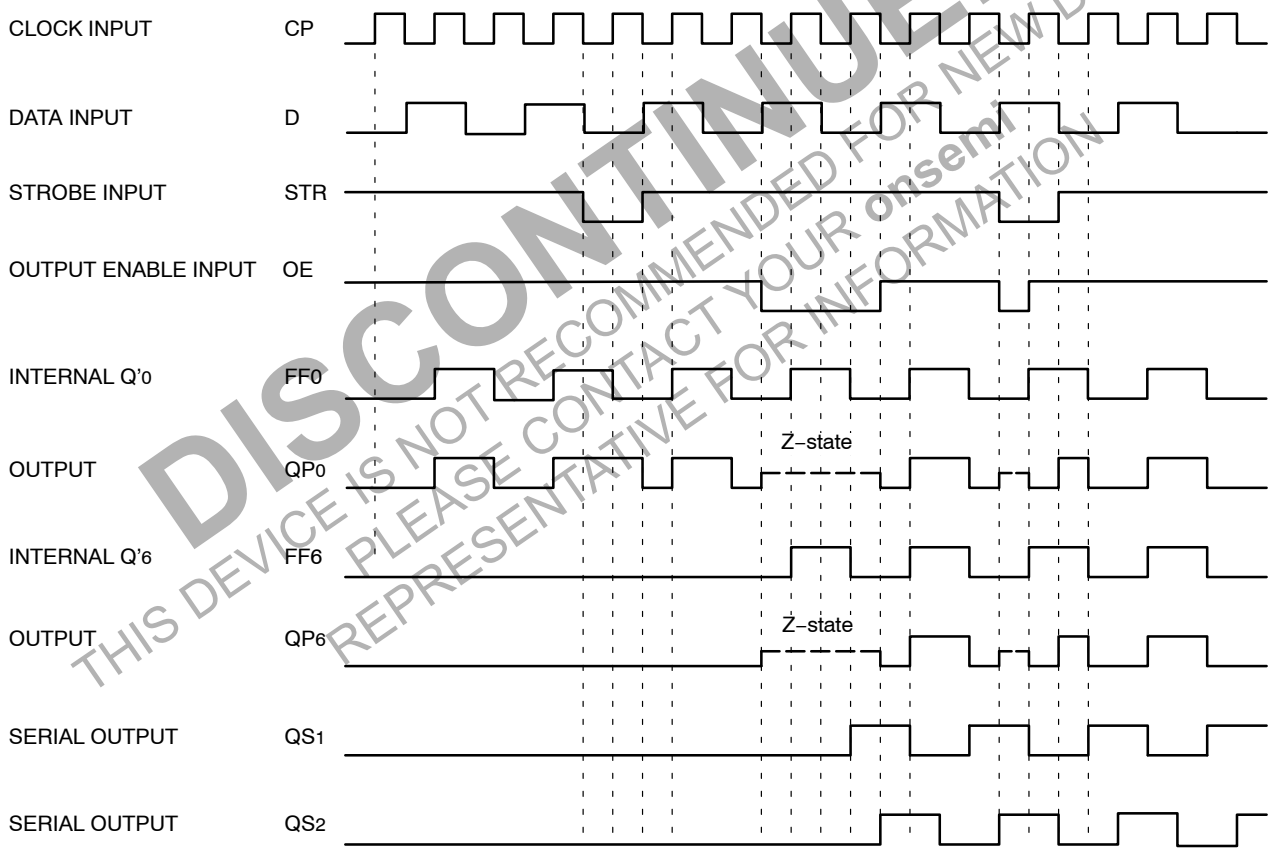


Figure 6. Timing Diagram

DC CHARACTERISTICS

Symbol	Parameter	Test Conditions	V_{CC} (V)	Guaranteed Limits			Unit
				−55°C to 25°C	≤ 85°C	≤ 125°C	
V_{IH}	Minimum High−Level Input Voltage	V_{OUT} = 0.1 V or V_{CC} − 0.1 V $\|I_{OUT}\| \le 20\ \mu A$	4.5	2.0	2.0	2.0	V
			5.5	2.0	2.0	2.0	
V_{IL}	Maximum Low−Level Input Voltage	V_{OUT} = 0.1 V or V_{CC} − 0.1 V $\|I_{OUT}\| \le 20\ \mu A$	4.5	0.8	0.8	0.8	V
			5.5	0.8	0.8	0.8	
V_{OH}	Minimum High−Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} $\|I_{OUT}\| \le 20\ \mu A$	4.5	4.4	4.4	4.4	V
			5.5	5.4	5.4	5.4	
		$V_{IN} = V_{IH}$ or V_{IL}, $\|I_{OUT}\| = 6$ mA	4.5	4.25	4.2	4.1	
V_{OL}	Maximum Low−Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL}, $\|I_{OUT}\| \le 20\ \mu A$	4.5	0.1	0.1	0.1	V
			5.5	0.1	0.1	0.1	
		$V_{IN} = V_{IH}$ or V_{IL}, $\|I_{OUT}\| = 6$ mA	4.5	0.25	0.3	0.4	
I_{IN}	Maximum Input Leakage Current	$V_{IN} = V_{CC}$ or GND	5.5	±0.1	±1	±1	μA
I_{OZ}	Maximum Tri−State Output Leakage Current	$V_{IN} = V_{CC}$ or GND $V_{OUT} = V_{CC}$ or GND	5.5	±0.5	±5	±10	μA
I_{CC}	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5	4.0	40	80	μA

ΔI_{CC}	Additional Quiescent Supply Current	V_{in} = 2.4V, Any One Input $V_{in} = V_{CC}$ or GND, Other Inputs I_{out} = 0μA		≥ −55°C	25 to 125°C	
			5.5	2.9	2.4	mA

AC CHARACTERISTICS ($t_f = t_r$ = 6 ns, C_L = 50 pF)

Symbol	Parameter	Test Conditions	V_{CC} (V)	Guaranteed Limits			Unit
				−55°C to 25°C	≤ 85°C	≤ 125°C	
t_{PHL}, t_{PLH}	Maximum Propagation Delay CP to QS_1	Figure 7	4.5	30	38	45	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay CP to QS_2	Figure 7	4.5	27	34	41	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay CP to QP_n	Figure 7	4.5	39	49	59	ns
t_{PHL}, t_{PLH}	Maximum Propagation Delay STR to QP_n	Figure 8	4.5	36	45	54	ns
t_{PZH}, t_{PZL}	Maximum 3−State Output Enable Time OE to QP_n	Figure 9	4.5	35	44	53	ns
t_{PHZ}, t_{PLZ}	Maximum 3−State Output Enable Time OE to QP_n	Figure 9	4.5	25	31	38	ns
t_{THL}, t_{TLH}	Maximum Output Transition Time	Figure 7	4.5	18	22	25	ns
t_W	Minimum Clock Pulse Width High or Low	Figure 7	4.5	16	20	24	ns
t_W	Minimum Strobe Pulse Width High	Figure 8	4.5	16	20	24	ns
t_{SU}	Minimum Set−up Time D to CP	Figure 10	4.5	10	13	15	ns
t_{SU}	Minimum Set−up Time CP to STR	Figure 8	4.5	20	25	30	ns
t_h	Minimum Hold Time D to CP	Figure 10	4.5	3	3	3	ns
t_h	Minimum Hold Time CP to STR	Figure 8	4.5	0	0	0	ns
f_{MAX}	Minimum Clock Pulse Frequency	Figure 7	4.5	30	24	20	MHz
C_{in}	Maximum Input Capacitance		−	10	10	10	pF
C_{out}	Maximum Output Capacitance		−	15	15	15	pF
C_{PD}	Power Dissipation Capacitance (Note 2)		−	140	140	140	pF

2. C_{PD} is defined as the value of the IC's equivalent capacitance from which the operating current can be calculated from: $I_{CC}(operating) \approx C_{PD} \times V_{CC} \times f_{IN} \times N_{SW}$ where N_{SW} = total number of outputs switching and f_{IN} = switching frequency.

AC WAVEFORMS

(V_M = 1.3 V)

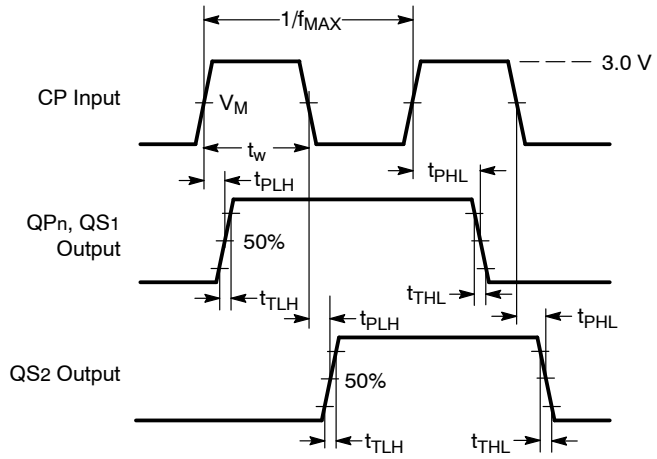


Figure 7. Waveforms showing the clock (CP) to output (QPn, QS1, QS2) propagation delays, the clock pulse width and the maximum clock frequency.

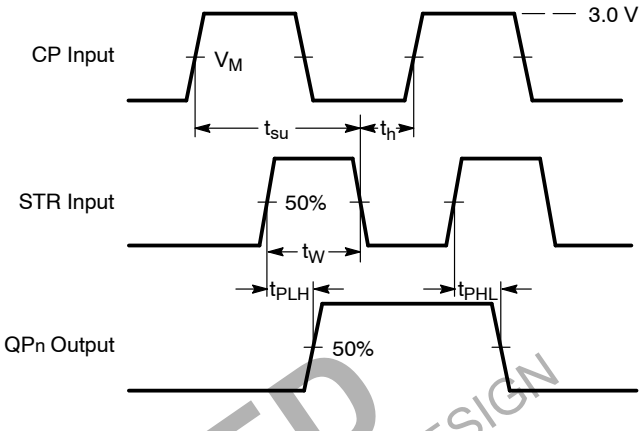


Figure 8. Waveforms showing the strobe (STR) to output (QPn) propagation delays, the strobe pulse width, the clock set−up and hold times for the strobe input.

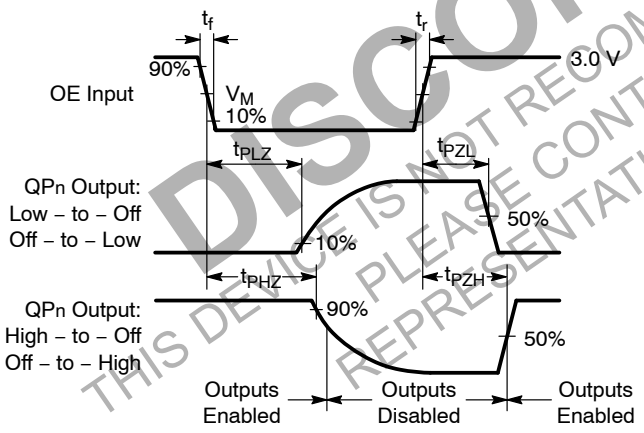
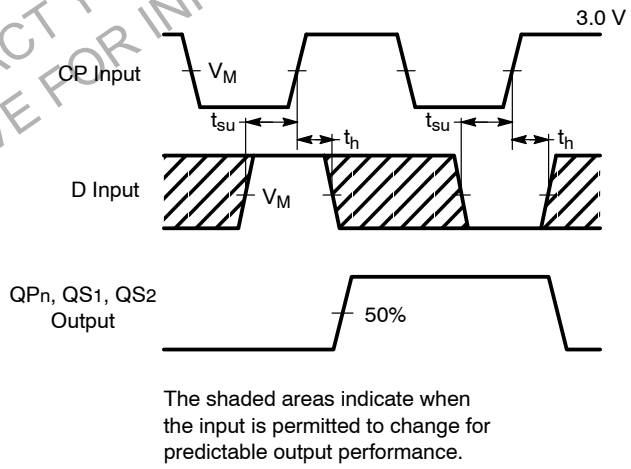


Figure 9. Waveforms showing the 3−state enable and disable times for input OE.



The shaded areas indicate when the input is permitted to change for predictable output performance.

Figure 10. Waveforms showing the data set−up and hold times for the data input.

TEST CIRCUITS

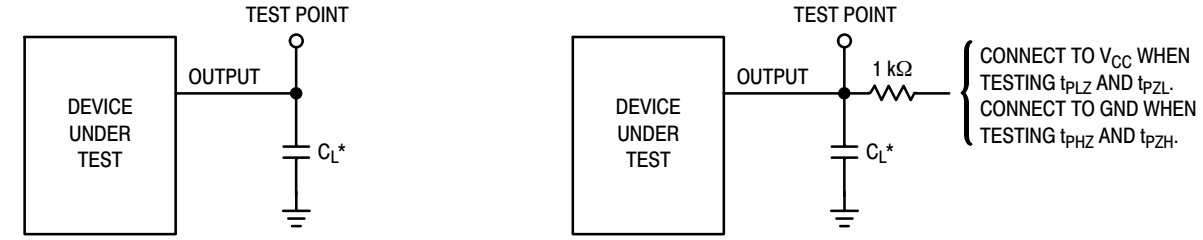


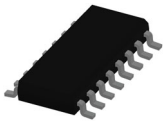
Figure 11. AC Characteristics Load Circuits

ORDERING INFORMATION

Device	Package	Shipping†
MC74HCT4094ADG	SOIC−16 (Pb−Free)	48 Units / Rail
MC74HCT4094ADR2G	SOIC−16 (Pb−Free)	2500 Tape & Reel
MC74HCT4094ADT	TSSOP−16*	96 Units / Rail
MC74HCT4094ADTR2G	TSSOP−16*	2500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This package is inherently Pb−Free.

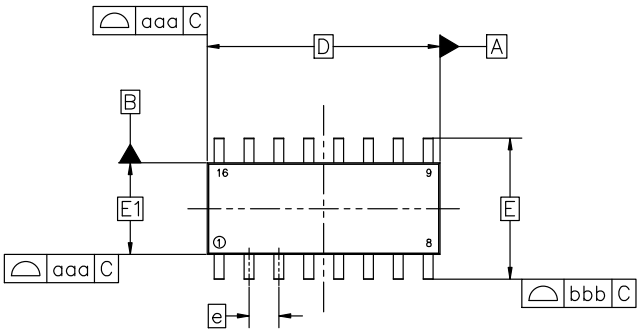
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



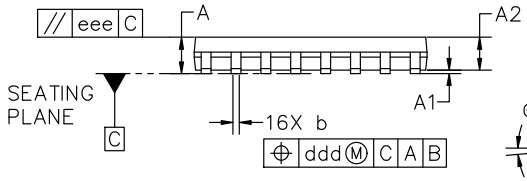
SOIC−16 9.90x3.90x1.50 1.27P
CASE 751B
ISSUE L

DATE 29 MAY 2024

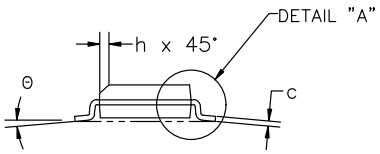
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. DIMENSION IN MILLIMETERS. ANGLE IN DEGREES.
3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15mm PER SIDE.
5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127mm TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION.



TOP VIEW

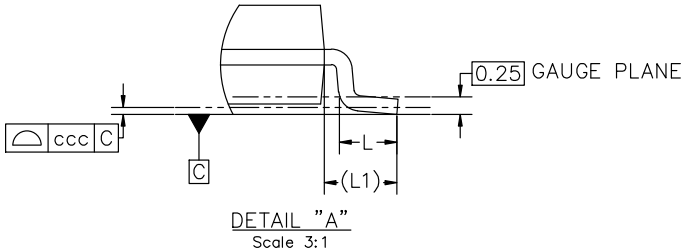


SIDE VIEW

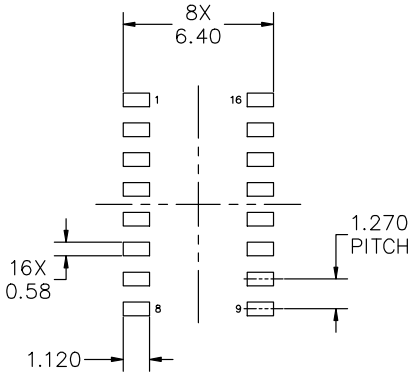


END VIEW

MILLIMETERS			
DIM	MIN	NOM	MAX
A	1.35	1.55	1.75
A1	0.00	0.05	0.10
A2	1.35	1.50	1.65
b	0.35	0.42	0.49
c	0.19	0.22	0.25
D	9.90 BSC		
E	6.00 BSC		
E1	3.90 BSC		
e	1.27 BSC		
h	0.25	−−−	0.50
L	0.40	0.83	1.25
L1	1.05 REF		
θ	0°	−−−	7°
TOLERANCE OF FORM AND POSITION			
aaa	0.10		
bbb	0.20		
ccc	0.10		
ddd	0.25		
eee	0.10		



DETAIL "A"
Scale 3:1



RECOMMENDED MOUNTING FOOTPRINT

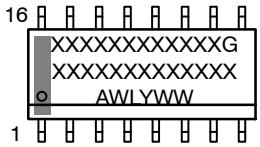
*FOR ADDITIONAL INFORMATION ON OUR PB−FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE onsemi SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D

DOCUMENT NUMBER:	98ASB42566B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SOIC−16 9.90X3.90X1.50 1.27P	PAGE 1 OF 2

SOIC−16 9.90x3.90x1.50 1.27P
CASE 751B
ISSUE L

DATE 29 MAY 2024

GENERIC
MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

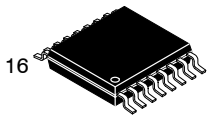
STYLE 1:		STYLE 2:		STYLE 3:		STYLE 4:	
PIN 1.	COLLECTOR	PIN 1.	CATHODE	PIN 1.	COLLECTOR, DYE #1	PIN 1.	COLLECTOR, DYE #1
2.	BASE	2.	ANODE	2.	BASE, #1	2.	COLLECTOR, #1
3.	EMITTER	3.	NO CONNECTION	3.	EMITTER, #1	3.	COLLECTOR, #2
4.	NO CONNECTION	4.	CATHODE	4.	COLLECTOR, #1	4.	COLLECTOR, #2
5.	EMITTER	5.	CATHODE	5.	COLLECTOR, #2	5.	COLLECTOR, #3
6.	BASE	6.	NO CONNECTION	6.	BASE, #2	6.	COLLECTOR, #3
7.	COLLECTOR	7.	ANODE	7.	EMITTER, #2	7.	COLLECTOR, #4
8.	COLLECTOR	8.	CATHODE	8.	COLLECTOR, #2	8.	COLLECTOR, #4
9.	BASE	9.	CATHODE	9.	COLLECTOR, #3	9.	BASE, #4
10.	EMITTER	10.	ANODE	10.	BASE, #3	10.	EMITTER, #4
11.	NO CONNECTION	11.	NO CONNECTION	11.	EMITTER, #3	11.	BASE, #3
12.	EMITTER	12.	CATHODE	12.	COLLECTOR, #3	12.	EMITTER, #3
13.	BASE	13.	CATHODE	13.	COLLECTOR, #4	13.	BASE, #2
14.	COLLECTOR	14.	NO CONNECTION	14.	BASE, #4	14.	EMITTER, #2
15.	EMITTER	15.	ANODE	15.	EMITTER, #4	15.	BASE, #1
16.	COLLECTOR	16.	CATHODE	16.	COLLECTOR, #4	16.	EMITTER, #1

STYLE 5:		STYLE 6:		STYLE 7:	
PIN 1.	DRAIN, DYE #1	PIN 1.	CATHODE	PIN 1.	SOURCE N-CH
2.	DRAIN, #1	2.	CATHODE	2.	COMMON DRAIN (OUTPUT)
3.	DRAIN, #2	3.	CATHODE	3.	COMMON DRAIN (OUTPUT)
4.	DRAIN, #2	4.	CATHODE	4.	GATE P-CH
5.	DRAIN, #3	5.	CATHODE	5.	COMMON DRAIN (OUTPUT)
6.	DRAIN, #3	6.	CATHODE	6.	COMMON DRAIN (OUTPUT)
7.	DRAIN, #4	7.	CATHODE	7.	COMMON DRAIN (OUTPUT)
8.	DRAIN, #4	8.	CATHODE	8.	SOURCE P-CH
9.	GATE, #4	9.	ANODE	9.	SOURCE P-CH
10.	SOURCE, #4	10.	ANODE	10.	COMMON DRAIN (OUTPUT)
11.	GATE, #3	11.	ANODE	11.	COMMON DRAIN (OUTPUT)
12.	SOURCE, #3	12.	ANODE	12.	COMMON DRAIN (OUTPUT)
13.	GATE, #2	13.	ANODE	13.	GATE N-CH
14.	SOURCE, #2	14.	ANODE	14.	COMMON DRAIN (OUTPUT)
15.	GATE, #1	15.	ANODE	15.	COMMON DRAIN (OUTPUT)
16.	SOURCE, #1	16.	ANODE	16.	SOURCE N-CH

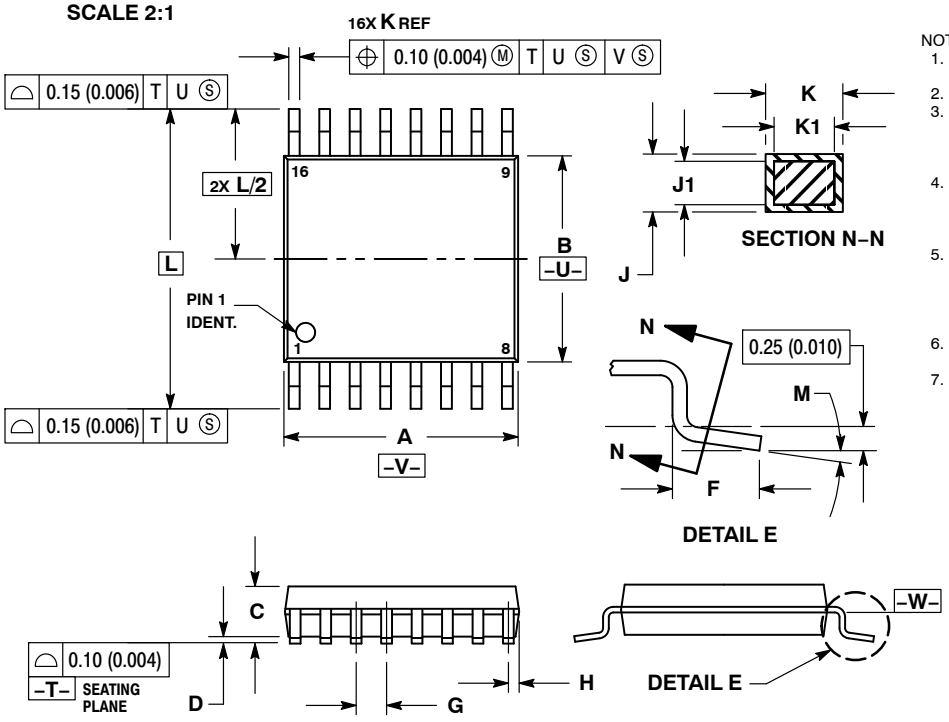
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

TSSOP−16 WB
CASE 948F
ISSUE B

DATE 19 OCT 2006



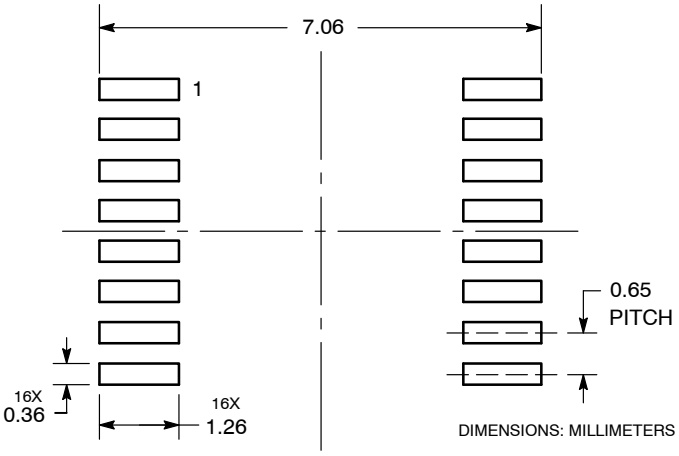
SCALE 2:1



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

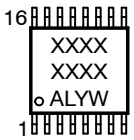
	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	−−−	1.20	−−−	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0 °	8 °	0 °	8 °

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX	= Specific Device Code
A	= Assembly Location
L	= Wafer Lot
Y	= Year
W	= Work Week
G or ▪	= Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present. Some products may not follow the Generic Marking.

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